Title (en)

DIE ASSEMBLY AND LOCATING METHOD

Title (de)

STEMPELANORDNUNG UND ORTUNGSVERFAHREN

Title (fr)

ENSEMBLE DE MATRICE ET PROCÉDÉ DE LOCALISATION

Publication

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Application

EP 17182687 A 20170721

Priority

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Abstract (en)

The invention provides a reusable assembly adapted for use in one or more of foiling, embossing and debossing. The assembly comprises a chase (104), having a first surface (114) with a plurality of user identifiable discrete grid positions (116) arranged within a grid and adapted for connection to a press. It further comprises a die assembly comprising a die (110) defining a first surface for foiling, embossing or debossing and connected to a linkage (106) defining a second surface (134) adapted for separable engagement with the first surface of the chase at various grid positions. A method of repositioning a die is also provided.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

- [XI] WO 0187602 A2 20011122 - SIL DIE SYSTEMS LTD [GB], et al
- [A] GB 2510809 A 20140820 - SIL DIE SYSTEMS LTD [GB]
- [A] US 6341557 B1 20020129 - HUTCHISON GLENN E [US], et al

Designated contracting state (EPC)

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